



Click [here](#) for the 3D model.

General Information

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|--------------------------|---|
| Series | SMD Comm X8G HT150C |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 190 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

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|--|---|
| Capacitance | 0.01 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 5% |
| Voltage DC | 100 VDC |
| Dielectric Withstanding Voltage | 250 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

Dimensions

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|-----------|-----------------|
| Chip Size | 2220 |
| L | 5.7mm +/-0.4mm |
| W | 5mm +/-0.4mm |
| T | 1.4mm +/-0.15mm |
| S | 3.5mm MIN |
| B | 0.6mm +/-0.35mm |

Packaging Specifications

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|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 1000 |